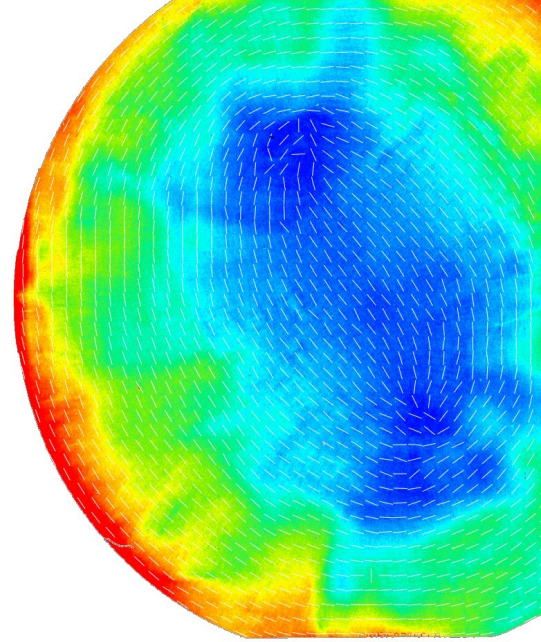


# residual stress measurement in SiC wafers



For reliable and precise residual stress measurement in SiC wafers, ilis has expanded its proven StrainScope® imaging polarimeter series with a new model. The distortion-free optics in combination with fully automatic stitching of wafers up to 200 mm in diameter make the new **StrainScope® Stepper** the perfect solution for this measurement task.

